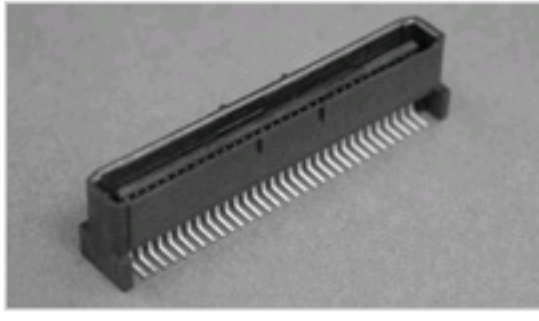




146888-1 Product Details

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1 mm Free Height (IEEE 1386)

1FHP,64,30A/P,S,C,S10,12,13,15

146888-1

TE Internal Number: 146888-1

Active
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Product Highlights [View All](#)

- Connector Style = Plug
- 64 Positions
- Stack Height = 10.00 mm, 12.00 mm, 13.00 mm, 15.00 mm
- With PCB Mount Retention
- With PCB Mount Alignment

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Please Note:
Use the Product Drawing for all design activity

Product Type Features	
PCB Mount Retention	With
PCB Mount Alignment	With
Product Type	Connector
Connector Type	Connector Assembly
Product Line	1.0 mm FH
CSA File Number	LR7189
PCB Mount Retention Type	Locating Post(s)
PCB Mounting Orientation	Vertical
PCB Mount Alignment Type	Locating Post(s)

Electrical Characteristics	
Contact - Rated Current (A)	0.8
Operating Voltage Reference	AC/DC
Operating Voltage (VAC)	250
Operating Voltage (VDC)	250

Termination Features	
Termination Method to PC Board	Surface Mount

Dimensions	
Stack Height (mm [in])	13.00 [0.512], 12.00 [0.472], 15.00 [0.591], 10.00 [0.394]
Tail Length (mm [in])	2.05 [0.081]
Length (X-Axis) (mm [in])	34.22 [1.347]
Width (Z-Axis) (mm [in])	6.04 [0.238]
Profile Height (Y-Axis) (mm [in])	8.38 [0.329]

Body Features	
Mating Retention	Without

Contact Features	
Contact Base Material	Phosphor Bronze
Contact Plating, Mating Area, Material	Gold
Contact Plating, Mating Area, Thickness (µm [µin])	0.76 [29.92]
Contact Plating, Termination Area, Material	Tin-Lead
Contact Plating, Termination Area, Thickness (µm [µin])	3.81 [150]
Underplate Material	Nickel
Underplate Material Thickness (µm [µin])	1.27 [50.000]
Contact Design	Single Beam
Pitch (mm [in])	16.00 [0.630]
Tin to Lead Ratio	93 / 7

Housing Features	
Connector Style	Plug
Centerline (mm [in])	1.00 [0.039]
Housing Color	Black
Mating Alignment	Without
Housing Material	Thermoplastic

Configuration Features	
Number of Positions	64
Number of Columns	32
Number of Rows	2
Differential Signaling	Yes
Tail Orientation	In-line

Industry Standards	
RoHS/ELV Compliance	ELV compliant, 5 of 6 Compliant
Lead Free Solder Processes	Reflow solder capable to 245°C, Reflow solder capable to 260°C
Industry Standard	IEEE 1386 Mezzanine Connector
Agency/Standard	CSA, UL
UL Rating	Listed
UL File Number	E28476
UL Flammability Rating	UL 94V-0
CSA Certified	Yes

Environmental	
Operating Temperature (°C [°F])	-55 - +110 [-67 - +230]

Conditions for Usage	
Applies To	Printed Circuit Board
Board-to-Board Configuration	Mezzanine

Operation/Application	
Pick and Place Cover	With
Application Use	Board-to-Board
Contact Transmits (Typical Application)	Signal (Data)

Packaging Features	
Packaging Method	Tape & Reel

Other	
Brand	AMP

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